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# ABSTRACT OF THE DISCLOSURE

0059 Within a method for fabricating a microelectronic, and a microelectronic fabrication fabricated in accord with the method, there is formed upon a bond pad formed over a substrate a conductor passivation layer. Within the method and the microelectronic fabrication, the bond pad is formed from a conductor material selected from the group consisting of aluminum and aluminum alloy conductor materials, and the conductor passivation layer is formed from a noble metal conductor material. The invention provides particular value for fabricating color filter sensor image array optoelectronic microelectronic fabrications with attenuated bond pad corrosion.

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